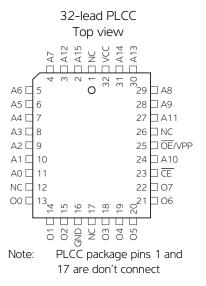


2. Pin configurations

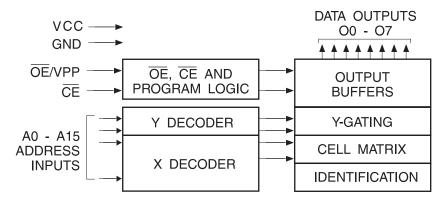
Pin name	Function
A0 - A15	Addresses
O0 - O7	Outputs
CE	Chip enable
OE/VPP	Output enable/ Program supply
NC	No connect



3. System Considerations

Switching between active and standby conditions via the chip enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device nonconformance. At a minimum, a $0.1\mu\text{F}$, high-frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a $4.7\mu\text{F}$ bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

Figure 3-1. Block diagram



4. Absolute maximum ratings*

Temperature under bias40°C to +85°C
Storage temperature65°C to +125°C
Voltage on any pin with respect to ground2.0V to +7.0V ⁽¹⁾
Voltage on A9 with respect to ground2.0V to +14.0V ⁽¹⁾
V _{PP} supply voltage with respect to ground2.0V to +14.0V ⁽¹⁾

*NOTICE: Stresses beyond those listed under "Absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended

periods may affect device reliability.

Note:

1. Minimum voltage is -0.6V DC, which may undershoot to -2.0V for pulses of less than 20ns. Maximum output pin voltage is $V_{CC} + 0.75V$ DC, which may be exceeded if certain precautions are observed (consult application notes), and which may overshoot to +7.0 volts for pulses of less than 20ns.

DC and AC characteristics

Table 5-1. Operating modes

Mode/Pin	Œ	OE/V _{PP}	Ai	V _{cc}	Outputs
Read ⁽²⁾	V _{IL}	V _{IL}	Ai	V _{CC}	D _{OUT}
Output disable ⁽²⁾	V_{IL}	V _{IH}	X ⁽¹⁾	V _{CC}	High Z
Standby ⁽²⁾	V _{IH}	×	X	V _{CC}	High Z
Rapid program ⁽³⁾	V _{IL}	V _{PP}	Ai	V _{CC}	D _{IN}
PGM inhibit ⁽³⁾	V _{IH}	V _{PP}	X	V _{CC}	High Z
Product identification ⁽³⁾⁽⁵⁾	$V_{\rm L}$	V _{IL}	$A9 = V_{H}^{(4)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A15 = V_{IL}$	V _{CC}	Identification code

Notes:

- X can be V_{II} or V_{IH}.
- 2. Read, output disable, and standby modes require $3.0V \le V_{CC} \le 3.6V$ or $4.5V \le V_{CC} \le 5.5V$.
- 3. Refer to programming characteristics. Programming modes require $V_{CC} = 6.5V$.
- 4. $V_H = 12.0 \pm 0.5 V$.
- 5. Two identifier bytes may be selected. All Ai inputs are held low (V_{L}) except A9, which is set to V_{H} , and A0, which is toggled low (V_{L}) to select the manufacturer's identification byte and high (V_{H}) to select the device code byte.

Table 5-2. DC and AC operating conditions for read operation

	Atmel AT27LV512A-90
Industrial operating temperature (case)	-40°C - 85°C
V. pouga gupelu	3.0V to 3.6V
V _{CC} power supply	5V ± 10%





Table 5-3. DC and operating characteristics for read operation

Symbol	Parameter	Condition	Min	Max	Units
V _{CC} = 3.0V	to 3.6V		,	'	
ILI	Input load current	$V_{IN} = 0V \text{ to } V_{CC}$		±1	μΑ
I _{LO}	Output leakage current	V _{OUT} = 0V to V _{CC}		±5	μΑ
I _{PP1} ⁽²⁾	V _{PP} ⁽¹⁾ read/standby current	$V_{PP} = V_{CC}$		10	μΑ
	V _{CC} ⁽¹⁾ standby current	I_{SB1} (CMOS), $\overline{CE} = V_{CC\pm} 0.3V$		20	μΑ
I _{SB}	V _{CC} Standby current	I_{SB2} (TTL), $\overline{CE} = 2.0 \text{ to } V_{CC} + 0.5V$		100	μΑ
I _{CC}	V _{CC} active current	$f = 5MHz$, $I_{OUT} = 0mA$, $\overline{CE} = V_{IL}$		8	mA
V _{IL}	Input low voltage		-0.6	0.8	V
V _{IH}	Input high voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output low voltage	I _{OL} = 2.0mA		0.4	V
V _{OH}	Output high voltage	I _{OH} = -2.0mA	2.4		V
V _{CC} = 4.5V	to 5.5V				
ILI	Input load current	$V_{IN} = 0V \text{ to } V_{CC}$		±1	μΑ
I _{LO}	Output leakage current	$V_{OUT} = OV \text{ to } V_{CC}$		±5	μΑ
I _{PP1} ⁽²⁾	V _{PP} ⁽¹⁾ read/standby current	$V_{PP} = V_{CC}$		10	μΑ
1	V (1) standby current	I_{SB1} (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μΑ
I _{SB}	V _{CC} ⁽¹⁾ standby current	I_{SB2} (TTL), \overline{CE} = 2.0 to V_{CC} + 0.5V		1	mA
I _{CC}	V _{CC} active current	$f = 5MHz$, $I_{OUT} = 0mA$, $\overline{CE} = V_{IL}$		20	mA
V _{IL}	Input low voltage		-0.6	0.8	V
V _{IH}	Input high voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output low voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output high voltage	Ι _{ΟΗ} = -400μΑ	2.4		V

Notes: 1. V_{CC} must be applied simultaneously with or before \overline{OE}/V_{pp} , and removed simultaneously with or after \overline{OE}/V_{pp} .

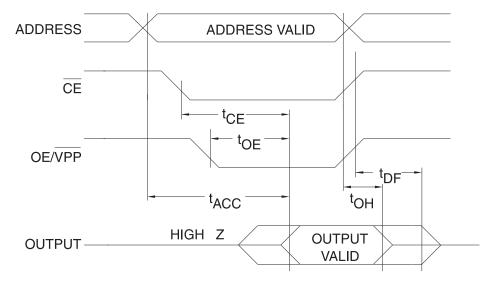
Table 5-4. AC characteristics for read operation

V_{CC} = 3.0V to 3.6V and 4.5V to 5.5V

			Atmel AT27LV512A-90		
Symbol	Parameter	Condition	Min	Max	Units
t _{ACC} (3)	Address to output delay	$\overline{CE} = \overline{OE}/V_{PP} = V_{IL}$		90	ns
t _{CE} ⁽²⁾	CE to output delay	$\overline{OE}/V_{PP} = V_{IL}$		90	ns
t _{OE} ⁽²⁾⁽³⁾	ŌĒ/V _{PP} to output delay	CE = V _{IL}		50	ns
t _{DF} ⁽⁴⁾⁽⁵⁾	OE/V _{PP} or CE high to output float, whichever occurred first			40	ns
t _{OH}	Output hold from address, $\overline{\text{CE}}$ or $\overline{\text{OE}}/\text{V}_{pp}$, whichever occurred first		0		ns

^{2.} $\overline{\text{OE}}/\text{V}_{pp}$ may be connected directly to V_{CC} , except during programming. The supply current would then be the sum of I_{CC} and I_{pp} .

Figure 5-1. AC waveforms for read operation⁽¹⁾



Notes:

- 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.
- 2. $\overline{\text{OE}}/\text{V}_{PP}$ may be delayed up to t_{CE} t_{OE} after the falling edge of $\overline{\text{CE}}$ without impact on t_{CE} -
- 3. $\overline{\text{OE}}/\text{V}_{\text{PP}}$ may be delayed up to t_{ACC} t_{OE} after the address is valid without impact on t_{ACC} .
- 4. This parameter is only sampled, and is not 100% tested.
- 5. Output float is defined as the point when data is no longer driven.

Figure 5-2. Input test waveforms and measurement levels

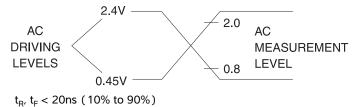
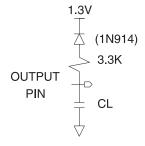


Figure 5-3. Output test load



Note: CL = 100pF including jig capacitance.





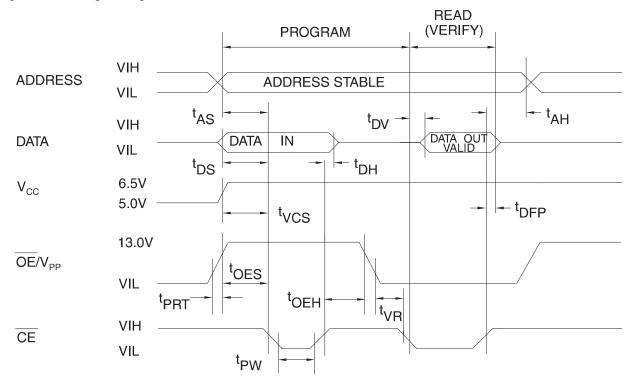
Table 5-5. Pin capacitance

 $f = 1MHz, T = 25^{\circ}C^{(1)}$

Symbol	Тур	Max	Units	Conditions
C _{IN}	4	6	pF	$V_{IN} = OV$
C _{OUT}	8	12	pF	V _{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled, and is not 100% tested.

Figure 5-4. Programming waveforms (1)



Notes: 1. The input timing reference is 0.8V for $V_{\parallel L}$ and 2.0V for $V_{\parallel H}$.

2. t_{OE} and t_{DFP} are characteristics of the device, but must be accommodated by the programmer.

Table 5-6. DC programming characteristics

 $T_A = 25 \pm 5$ °C, $V_{CC} = 6.5 \pm 0.25$ V, $\overline{OE}/V_{PP} = 13.0 \pm 0.25$ V

			Limits		
Symbol	Parameter	Test conditions	Min	Max	Units
I _{LI}	Input load current	$V_{IN} = V_{IL}, V_{IH}$		10	μΑ
V _{IL}	Input low level		-0.6	0.8	V
V _{IH}	Input high level		2.0	V _{CC} + 0.5	V
V _{OL}	Output low voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output high voltage	I _{OH} = -400μA	2.4		V
I _{CC2}	V _{CC} supply current (program and verify)			25	mA
I _{PP2}	ŌĒ/V _{pp} current	CE = V _{IL}		25	mA
V _{ID}	A9 product identification voltage		11.5	12.5	V

Table 5-7. AC programming characteristics

 $T_A = 25 \pm 5$ °C, $V_{CC} = 6.5 \pm 0.25$ V, $\overline{OE}/V_{PP} = 13.0 \pm 0.25$ V

			Lin	nits	
Symbol	Parameter	Test conditions ⁽¹⁾	Min	Max	Units
t _{AS}	Address setup time		2		μs
t _{OES}	OE/V _{PP} setup time		2		μs
t _{OEH}	OE/V _{PP} hold time	Input rise and fall times:	2		μs
t _{DS}	Data setup time	(10% to 90%) 20ns	2		μs
t _{AH}	Address hold time	Input pulse levels:	0		μs
t _{DH}	Data hold time	0.45V to 2.4V	2		μs
t _{DFP}	CE high to output float delay ⁽²⁾		0	130	ns
t _{VCS}	V _{CC} setup time	Input timing reference level: 0.8V to 2.0V	2		μs
t _{PW}	CE program pulse width ⁽³⁾	- 0.60 to 2.00	95	105	μs
t _{DV}	Data valid from $\overline{\text{CE}}^{(2)}$	Output timing reference level:		1	μs
t _{VR}	OE/V _{PP} recovery time	0.8V to 2.0V	2		μs
t _{PRT}	OE/V _{PP} pulse rise time during programming		50		ns

Notes: 1. V_{CC} must be applied simultaneously with or before \overline{OE}/V_{PP} and removed simultaneously with or after \overline{OE}/V_{PP} .

- 2. This parameter is only sampled, and is not 100% tested. Output float is defined as the point where data is no longer driven. See timing diagram.
- 3. Program pulse width tolerance is $100\mu s \pm 5\%$.

Table 5-8. The Atmel AT27LV512A integrated product identification code⁽¹⁾

		Pins								
Codes	A0	07	O6	O5	04	О3	02	01	00	Hex data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device type	1	0	0	0	0	0	1	0	1	0D

Note: 1. The Atmel AT27LV512A has the same product identification code as the Atmel AT27C512R. Both are programming compatible.

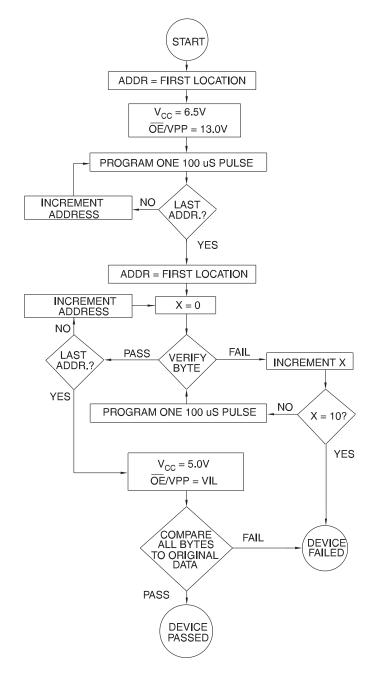




6. Rapid programming algorithm

A 100 μ s $\overline{\text{CE}}$ pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and $\overline{\text{OE}}/V_{pp}$ is raised to 13.0V. Each address is first programmed with one 100 μ s $\overline{\text{CE}}$ pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100 μ s pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. $\overline{\text{OE}}/V_{pp}$ is then lowered to V_{lL} and V_{CC} to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.

Figure 6-1. Rapid programming algorithm



8

7. Ordering information

Green package (Pb/halide-free)

t _{ACC}	I _{CC} (mA)					
(ns)	Active	Standby	Atmel ordering code	Package	Lead finish	Operation range
90	8	0.02	AT27LV512A-90JU	32 J	Matte tin	Industrial (-40°C to 85°C)

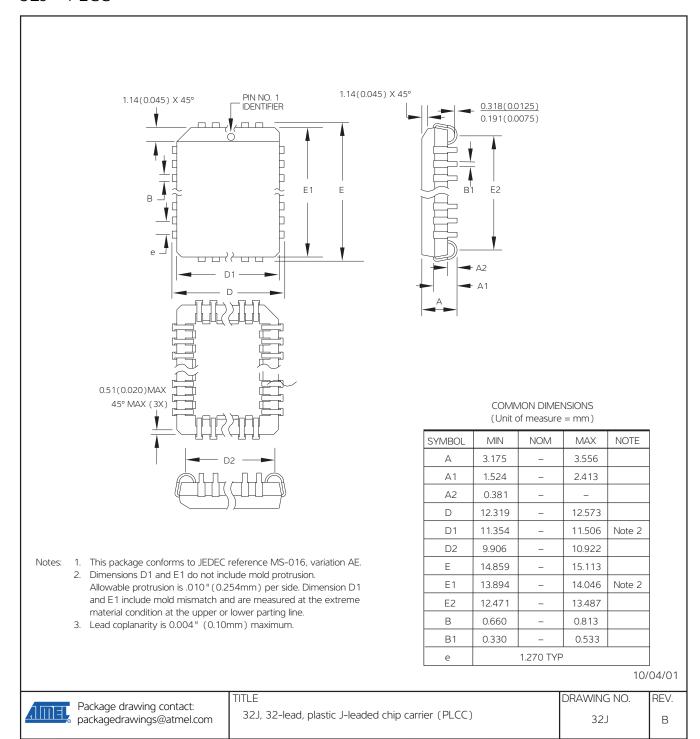
	Package type
32J	32-lead, plastic, J-leaded chip carrier (PLCC)





8. Packaging information

32J – PLCC



9. Revision history

Doc. rev.	Date	Comments
0607G	04/2011	Remove SOIC and TSOP packages
		Add lead finish to ordering information
0607F	12/2007	





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